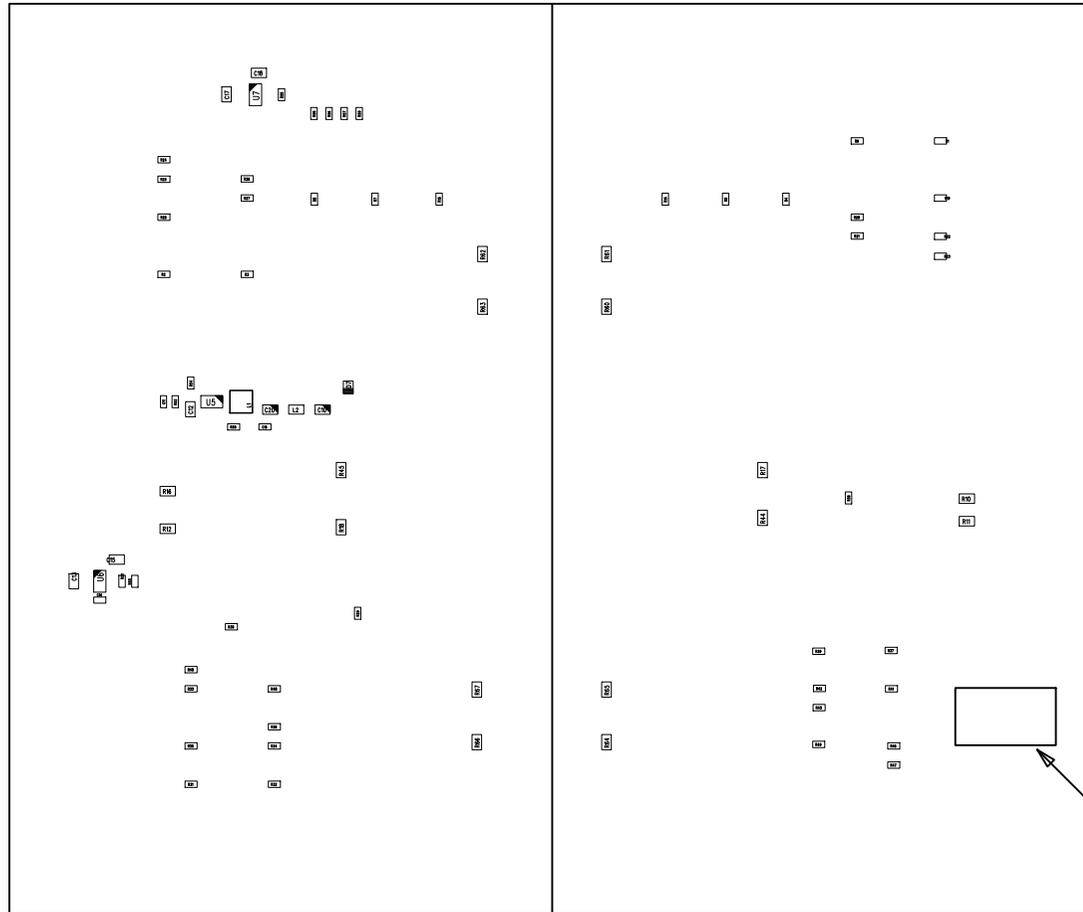


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
	3	Production	E Benedict	4 OCT 18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
6. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
7. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
- ⑧ APPLY DEMO S/N LABEL IN THIS AREA
- ⑨ BREAK BOARDS AS A SET. DO NOT BREAK AT THIS LOCATION

APPROVALS			1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.infnear.com ADI CONFIDENTIAL- FOR CUSTOMER USE ONLY	
PCB DES.	EB		TITLE: BOTTOM ASSEMBLY DEMO CIRCUIT RUGGED I2C SLAVE DEVICE EXTENDER	
APP ENG.	EB			
		SIZE	IC NO. LTC4331	REV.
		N/A	DEMO CIRCUIT DC2754A	3
SCALE = NONE		SHT 2 OF 2		